

UNISONIC TECHNOLOGIES CO., LTD

2NM80 **Preliminary** Power MOSFET

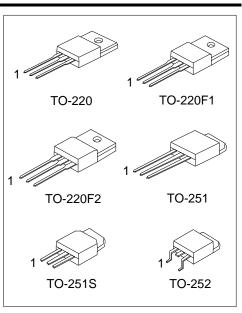
2A, 800V N-CHANNEL SUPER-JUNCTION MOSFET

DESCRIPTION

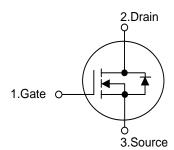
The UTC 2NM80 is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at AC-DC converters for power applications.

FEATURES

- * $R_{DS(ON)} \le 3.7 \Omega @ V_{GS} = 10V, I_D = 1.0A$
- * Fast switching capability
- * Avalanche energy tested
- * Improved dv/dt capability, high ruggedness



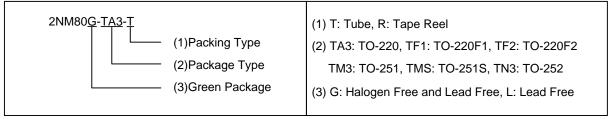
SYMBOL



ORDERING INFORMATION

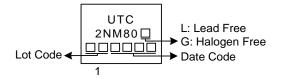
Ordering Number		Daakaas	Pin Assignment			Packing	
Lead Free	Halogen Free	Package	1	2	2 3		
2NM80L-TA3-T	2NM80G-TA3-T	TO-220	G	D	S	Tube	
2NM80L-TF1-T	2NM80G-TF1-T	TO-220F1	G	D	S	Tube	
2NM80L-TF2-T	2NM80G-TF2-T	TO-220F2	G	D	S	Tube	
2NM80L-TM3-T	2NM80G-TM3-T	TO-251	G	D	S	Tube	
2NM80L-TMS-T	2NM80G-TMS-T	TO-251S	G	D	S	Tube	
2NM80L-TN3-R	2NM80G-TN3-R	TO-252	G	D	S	Tape Reel	

Note: Pin Assignment: G: Gate D: Drain S: Source



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■ MARKING



■ **ABSOLUTE MAXIMUM RATINGS** (T_C = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	800	V
Gate-Source Voltage		V_{GSS}	±30	V
Drain Current	Continuous	I_{D}	2.0	Α
	Pulsed (Note 2)	I_{DM}	8.0	Α
Avalanche Current (Note 2)		I_{AR}	1.3	Α
Avalanche Energy	Single Pulsed (Note 3)	E _{AS}	134	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	3.5	V/ns
Power Dissipation	TO-220		32	W
	TO-220F1/TO-220F2	Б.	20	W
	TO-251/TO-251S TO-252	P_D	21	W
Junction Temperature		TJ	+150	°C
Storage Temperature		T _{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L=159mH, I_{AS} =1.3A, V_{DD} =50V, R_{G} =25 Ω , Starting T_{J} = 25°C
- 4. $I_{SD} \le 2.0A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25$ °C

■ THERMAL DATA

PARAMETER		SYMBOL	RATING	UNIT
Junction to Ambient	TO-220/TO-220F1 TO-220F2		62.5	°C/W
	TO-251/TO-251S TO-252	$ heta_{JA}$	110	°C/W
Junction to Case	TO-220		3.91	°C/W
	TO-220F1/TO-220F2	0	6.25	°C/W
	TO-251/TO-251S TO-252	θυς	5.95 (Note)	°C/W

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

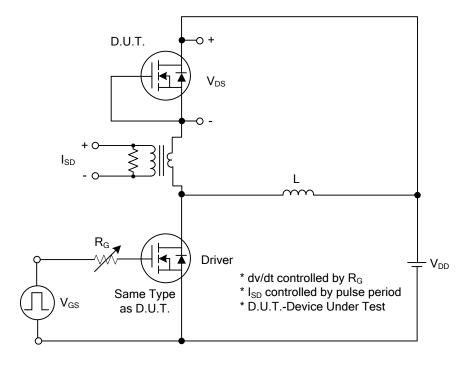
■ **ELECTRICAL CHARACTERISTICS** (T_J =25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	800			V		
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 800V, V_{GS} = 0V$			10	μΑ		
Gate-Source Leakage Current	I _{GSS}	$V_{GS} = 30V, V_{DS} = 0V$			100	nA		
Gate-Source Leakage Current		$V_{GS} = -30V, V_{DS} = 0V$			-100	nA		
ON CHARACTERISTICS								
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	2.5		4.5	V		
Static Drain-Source On-State Resistance	R _{DS(ON)}	$V_{GS} = 10V, I_D = 1.0A$			3.7	Ω		
DYNAMIC CHARACTERISTICS								
Input Capacitance	C _{ISS}			270		pF		
Output Capacitance	Coss	V_{GS} =0V, V_{DS} =25V, f=1.0MHz		85		pF		
Reverse Transfer Capacitance	C_{RSS}			8		pF		
SWITCHING CHARACTERISTICS								
Total Gate Charge (Note 1)	Q_G	\		35		nC		
Gate to Source Charge	Q_GS	V_{DS} =50V, I_{D} =1.3A, I_{G} =100 μ A V_{GS} =10V (Note 1,2)		3.5		nC		
Gate to Drain Charge	Q_GD			7		nC		
Turn-ON Delay Time (Note 1)	t _{D(ON)}	$V_{DD} = 30V, I_D = 0.5A, R_G = 25\Omega,$		32		nS		
Rise Time	t_R			42		nS		
Turn-OFF Delay Time	t _{D(OFF)}	V _{GS} =10V (Note 1,2)		92		nS		
Fall-Time	t_{F}			26		nS		
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS								
Maximum Body-Diode Continuous Current	Is				2	Α		
Maximum Body-Diode Pulsed Current	I _{SM}				8	Α		
Drain-Source Diode Forward Voltage (Note 1)	V_{SD}	I _S =2.0A, V _{GS} =0V			1.4	V		
Body Diode Reverse Recovery Time (Note 1)	t _{rr}	I _S =2.0A, V _{GS} =0V		300		nS		
Body Diode Reverse Recovery Charge	Q_{rr}	dI _F /dt=100A/μs		1.55		μC		

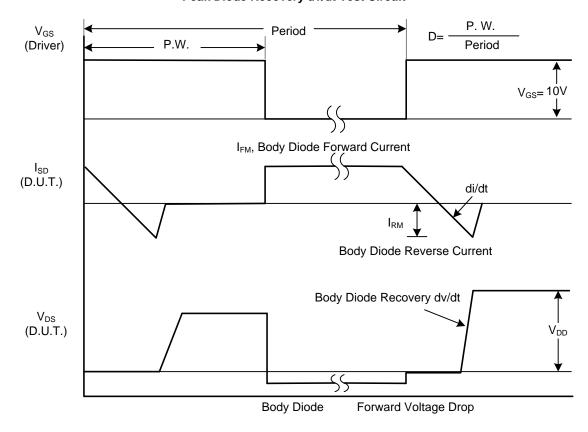
Notes: 1. Pulse Test : Pulse width ≤ 300µs, Duty cycle ≤ 2%.

^{2.} Essentially independent of operating ambient temperature.

■ TEST CIRCUITS AND WAVEFORMS

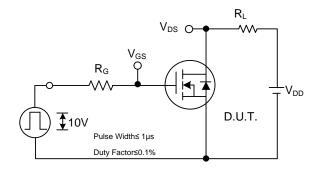


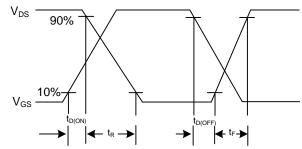
Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

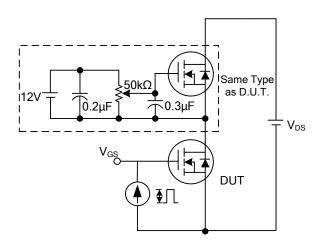
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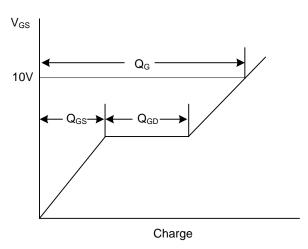




Switching Test Circuit

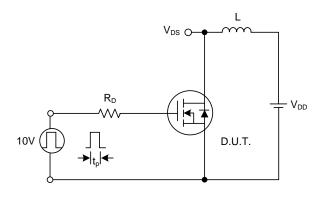
Switching Waveforms

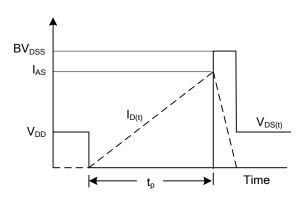




Gate Charge Test Circuit

Gate Charge Waveform





Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms

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